Low-Voltage CMOS Octal Transceiver

With 5 V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The MC74LCX245 is a high performance, non–inverting octal transceiver operating from a 2.0 to 5.5 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V $_{\rm I}$ specification of 5.5 V allows MC74LCX245 inputs to be safely driven from 5 V devices if V $_{\rm CC}$ is less than 5.0 V. The MC74LCX245 is suitable for memory address driving and all TTL level bus oriented transceiver applications.

Current drive capability is 24 mA at both A and B ports. The Transmit/Receive (T/\overline{R}) input determines the direction of data flow through the bi-directional transceiver. Transmit (active-HIGH) enables data from A ports to B ports; Receive (active-LOW) enables data from B to A ports. The Output Enable input, when HIGH, disables both A and B ports by placing them in a HIGH Z condition.

Features

- Designed for 2.0 to 5.5 V V_{CC} Operation
- 5 V Tolerant Interface Capability With 5 V TTL Logic
- Supports Live Insertion and Withdrawal
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0$ V
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10 μA)
 Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V

Machine Model >200 V

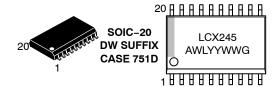
Pb–Free Packages are Available*



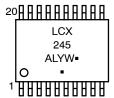
ON Semiconductor®

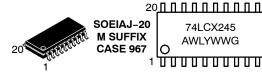
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MARKING DIAGRAMS



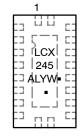








QFN20 MN SUFFIX CASE 485AA



A = Assembly Location

L, WL = Wafer Lot Y, YY = Year W, WW = Work Week G or • = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

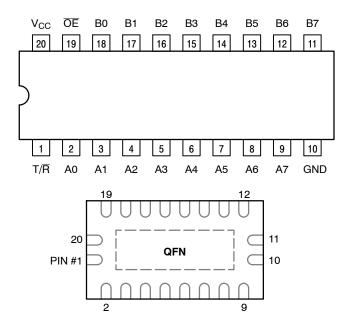


Figure 1. Pinout (Top View)

PIN NAMES

PINS	FUNCTION
ŌĒ	Output Enable Input
T/R	Transmit/Receive Input
A0-A7	Side A 3-State Inputs or 3-State Outputs
B0-B7	Side B 3-State Inputs or 3-StateOutputs

TRUTH TABLE

INF	PUTS	OPERATING MODE
ŌĒ	T/R	Non-Inverting
L	L	B Data to A Bus
L	Н	A Data to B Bus
Н	Х	Z

H = High Voltage Level

L = Low Voltage Level

Z = High Impedance State

X = High or Low Voltage Level and Transitions are Acceptable

For I_{CC} reasons, Do Not Float Inputs

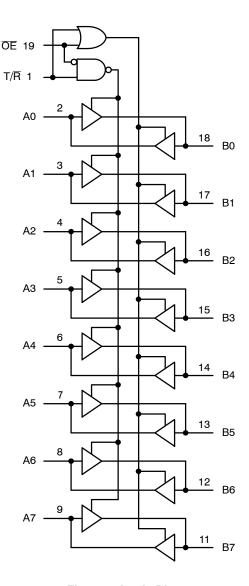


Figure 2. Logic Diagram

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V_{CC}	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_1 \le +7.0$		V
Vo	DC Output Voltage	$-0.5 \le V_0 \le +7.0$	Output in 3-State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
Io	DC Output Source/Sink Current	±50		mA
Icc	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Max	Unit
V _{CC}	Supply Voltage	Operating Data Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	5.5 5.5	V
VI	Input Voltage		0		5.5	V
V _O	Output Voltage	(HIGH or LOW State) (3-State)	0 0		V _{CC} 5.5	V
I _{OH}	HIGH Level Output Current	V _{CC} = 3.0 V - 3.6 V V _{CC} = 2.7 V - 3.0 V V _{CC} = 2.3 V - 2.7 V			- 24 - 12 - 8	mA
I _{OL}	LOW Level Output Current	V _{CC} = 3.0 V - 3.6 V V _{CC} = 2.7 V - 3.0 V V _{CC} = 2.3 V - 2.7 V			+ 24 + 12 + 8	mA
T _A	Operating Free-Air Temperature		-55		+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, V _{IN} from 0.	8 V to 2.0 V, V _{CC} = 3.0 V	0		10	ns/V

^{1.} I_{O} absolute maximum rating must be observed.

DC ELECTRICAL CHARACTERISTICS

			T _A = -55°C	to +125°C	
Symbol	Characteristic	Condition	Min	Max	Unit
V_{IH}	HIGH Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V	1.7		V
		2.7 V ≤ V _{CC} ≤ 3.6 V	2.0		
V _{IL}	LOW Level Input Voltage (Note 2)	$2.3 \text{ V} \le \text{V}_{CC} \le 2.7 \text{ V}$		0.7	٧
		$2.7 \text{ V} \leq \text{V}_{CC} \leq 3.6 \text{ V}$		0.8	
V _{OH}	HIGH Level Output Voltage	$2.3~V \le V_{CC} \le 3.6~V;~I_{OL}$ = 100 μA	V _{CC} - 0.2		٧
		V_{CC} = 2.3 V; I_{OH} = -8 mA	1.8		
		$V_{CC} = 2.7 \text{ V}; I_{OH} = -12 \text{ mA}$	2.2		
		$V_{CC} = 3.0 \text{ V}; I_{OH} = -18 \text{ mA}$	2.4		
		$V_{CC} = 3.0 \text{ V}; I_{OH} = -24 \text{ mA}$	2.2		
V _{OL}	LOW Level Output Voltage	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{ I}_{OL} = 100 \mu\text{A}$		0.2	V
		V _{CC} = 2.3 V; I _{OL} = 8 mA		0.6	
		$V_{CC} = 2.7 \text{ V}; I_{OL} = 12 \text{ mA}$		0.4	
		V _{CC} = 3.0 V; I _{OL} = 16 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 24 mA		0.55	
I _I	Input Leakage Current	$2.3 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{I} \le 5.5 \text{ V}$		±5	μΑ
I _{OZ}	3-State Output Current	$2.3 \le V_{CC} \le 3.6 \text{ V}; \ 0V \le V_{O} \le 5.5 \text{ V}; \ V_{I} = V_{IH} \ \text{or V}_{IL}$		±5	μΑ
l _{OFF}	Power-Off Leakage Current	$V_{CC} = 0 \text{ V}; V_{I} \text{ or } V_{O} = 5.5 \text{ V}$		10	μΑ
Icc	Quiescent Supply Current	$2.3 \le V_{CC} \le 3.6 \text{ V}; V_I = \text{GND or } V_{CC}$		10	μΑ
		$2.3 \le V_{CC} \le 3.6 \text{ V}; 3.6 \le V_{I} \text{ or } V_{O} \le 5.5 \text{ V}$		±10	
ΔI_{CC}	Increase in I _{CC} per Input	$2.3 \le V_{CC} \le 3.6 \text{ V}; V_{IH} = V_{CC} - 0.6 \text{ V}$		500	μΑ

^{2.} These values of V_{\parallel} are used to test DC electrical characteristics only.

AC CHARACTERISTICS $t_R=t_F$ = 2.5 ns; R_L = 500 Ω

				Limits							
				T _A	= -55°C	to +125°C					
			V _{CC} = 3.3	3 V ± 0.3V	V _{CC} =	2.7 V	V _{CC} = 2.5	$V \pm 0.2V$	V _{CC} =	5.0 V	
			C _L =	50 pF	C _L =	50 pF	C _L = 3	30 pF	C _L =	50 pF	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay Input to Output	1	1.5 1.5	7.0 7.0	1.5 1.5	8.0 8.0	1.5 1.5	8.4 8.4	1.5 1.5	5.0 5.0	ns
t _{PZH}	Output Enable Time to High and Low Level	2	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	1.5 1.5	10.5 10.5	1.5 1.5	7.0 7.0	ns
t _{PHZ}	Output Disable Time From High and Low Level	2	1.5 1.5	7.5 7.5	1.5 1.5	8.5 8.5	1.5 1.5	9.0 9.0	1.5 1.5	6.0 6.0	ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 3)			1.0 1.0		1.0 1.0		1.0 1.0		1.0 1.0	ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

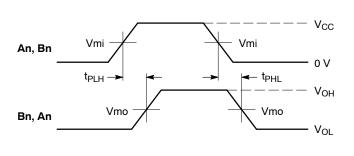
DYNAMIC SWITCHING CHARACTERISTICS

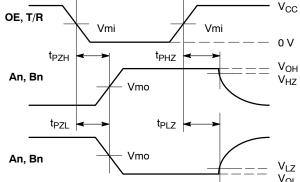
			T,	_A = +25°	С	
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V _{OLP}	Dynamic LOW Peak Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ $V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$		0.8 0.6		V V
V _{OLV}	Dynamic LOW Valley Voltage (Note 4)	$\begin{aligned} &V_{CC} = 3.3 \text{ V, } C_L = 50 \text{ pF, } V_{IH} = 3.3 \text{ V, } V_{IL} = 0 \text{ V} \\ &V_{CC} = 2.5 \text{ V, } C_L = 30 \text{ pF, } V_{IH} = 2.5 \text{ V, } V_{IL} = 0 \text{ V} \end{aligned}$		-0.8 -0.6		V V

^{4.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	7	pF
C _{I/O}	Input/Output Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	25	pF



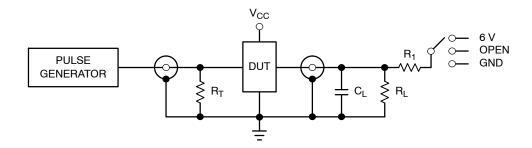


$\label{eq:waveform 1 - PROPAGATION DELAYS} t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

WAVEFORM 2 – OUTPUT ENABLE AND DISABLE TIMES $t_R=t_F=2.5~\text{ns},\,10\%$ to $90\%;\,f=1~\text{MHz};\,t_W=500~\text{ns}$

Figure 3. AC Waveforms

	V _{CC}					
Symbol	3.3 V ± 0.3 V	2.7 V	2.5 V ± 0.2 V	5.0 V		
Vmi	1.5 V	1.5 V	V _{CC} /2	V _{CC} /2		
Vmo	1.5 V	1.5 V	V _{CC} /2	V _{CC} /2		
V _{HZ}	V _{OL} + 0.3 V	V _{OL} + 0.3 V	V _{OL} + 0.15 V	V _{OL} + 0.15 V		
V_{LZ}	V _{OH} – 0.3 V	V _{OH} – 0.3 V	V _{OH} – 0.15 V	V _{OH} – 0.15 V		



TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6 V at V_{CC} = 3.3 \pm 0.3 V 6 V at V_{CC} = 2.5 \pm 0.2 V
Open Collector/Drain t _{PLH} and t _{PHL}	6 V
t _{PZH} , t _{PHZ}	GND

 C_L = 50 pF at V_{CC} = 3.3 \pm 0.3 V or equivalent (includes jig and probe capacitance) C_L = 30 pF at V_{CC} = 2.5 \pm 0.2 V or equivalent (includes jig and probe capacitance) R_L = R_1 = 500 Ω or equivalent

 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

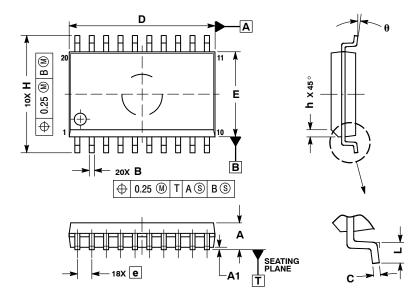
ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LCX245DW	SOIC-20	38 Units / Rail
MC74LCX245DWG	SOIC-20 (Pb-Free)	38 Units / Rail
MC74LCX245DWR2	SOIC-20	1000 Tape & Reel
MC74LCX245DWR2G	SOIC-20 (Pb-Free)	1000 Tape & Reel
MC74LCX245DT	TSSOP-20*	75 Units / Rail
MC74LCX245DTG	TSSOP-20* (Pb-Free)	75 Units / Rail
MC74LCX245DTR2	TSSOP-20*	2000 Tape & Reel
MC74LCX245DTR2G	TSSOP-20* (Pb-Free)	2000 Tape & Reel
MC74LCX245M	SOEIAJ-20	40 Units / Rail
MC74LCX245MG	SOEIAJ-20 (Pb-Free)	40 Units / Rail
MC74LCX245MEL	SOEIAJ-20	2000 Tape & Reel
MC74LCX245MELG	SOEIAJ-20 (Pb-Free)	2000 Tape & Reel
MC74LCX245MNTWG	QFN20 (Pb-Free)	3000 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. *This package is inherently Pb-Free.

PACKAGE DIMENSIONS

SOIC-20 **DW SUFFIX** CASE 751D-05 **ISSUE G**



NOTES:

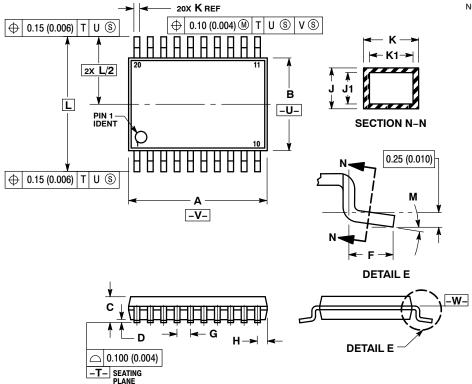
- NOTES:

 1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS				
DIM	MIN	MAX			
Α	2.35	2.65			
A1	0.10	0.25			
В	0.35	0.49			
С	0.23	0.32			
D	12.65	12.95			
E	7.40	7.60			
е	1.27	BSC			
Н	10.05	10.55			
h	0.25	0.75			
L	0.50	0.90			
θ	0 °	7 °			

PACKAGE DIMENSIONS

TSSOP-20 **DT SUFFIX** CASE 948E-02 **ISSUE B**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION:

 - MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS
 - BURRS. MOLD FLASH OR GATE BURR SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

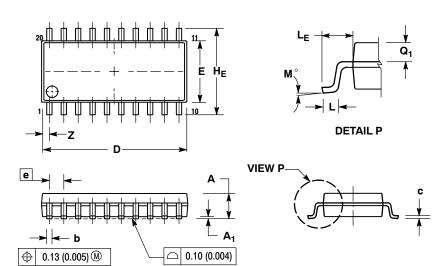
 5. DIMENSION K DOES NOT INCLUDE.
 - SIDE.
 5. DIMENSION K DOES NOT INCLUDE
 DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08
 (0.003) TOTAL IN EXCESS OF THE K
 DIMENSION AT MAXIMUM MATERIAL
 CONDITION.

 - DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
Ĺ	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

PACKAGE DIMENSIONS

SOEIAJ-20 **M SUFFIX** CASE 967-01 **ISSUE A**

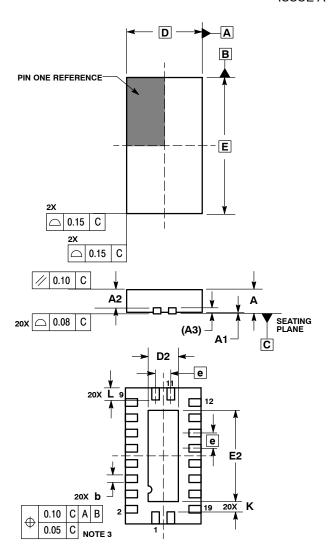


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
Q_1	0.70	0.90	0.028	0.035
Z		0.81		0.032

PACKAGE DIMENSIONS

QFN20 CASE 485AA-01 **ISSUE A**



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. DIMENSIONS 6 APPLIES TO PLATED
- DIMENSIONS APPLIES TO FLATER
 TERMINAL AND IS MEASURED BETWEEN
 0.25 AND 0.30 MM FROM TERMINAL.
 COPLANARITY APPLIES TO THE EXPOSED
 PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1	0.00	0.05	
A2	0.65	0.75	
A3	0.20 REF		
b	0.20	0.30	
D	2.50 BSC		
D2	0.85	1.15	
E	4.50 BSC		
E2	2.85	3.15	
е	0.50 BSC		
K	0.20		
L	0.35	0.45	

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MC74LCX245/D